

# Global System-In-Package (Sip) Die Market Professional Survey Report 2017

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## Abstracts

This report studies System-In-Package (Sip) Die in Global market, especially in North America, China, Europe, Southeast Asia, Japan and India, with production, revenue, consumption, import and export in these regions, from 2012 to 2016, and forecast to 2022.

This report focuses on top manufacturers in global market, with production, price, revenue and market share for each manufacturer, covering

ASE Global (Taiwan)

Chipmos Technologies (Taiwan)

Nanium S.A. (Portugal)

Siliconware Precision Industries

Wi2Wi Inc. (U.S.)

Insightsip (France)

Fujitsu Semiconductor Limited (Japan)

Amkor Technology (U.S)

Freescale Semiconductor Inc. (U.S.)

## By Packaging Technology

2D IC Packaging

3D IC Packaging

On the basis of product, this report displays the production, revenue, price, market share and growth rate of each type, primarily split into

Surface Mount Technology (SMT)

Small Outline Package (SOP)

Ball Grid Array (BGA)

Quad Flat Package. (QFP)

By Application, the market can be split into

Consumer Electronics

Automotive

Networking

Medical Electronics

Computing

Mobile

Communication

By Regions, this report covers (we can add the regions/countries as you want)

North America

China

Europe

Southeast Asia

Japan

India

If you have any special requirements, please let us know and we will offer you the report as you want.

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Data Source

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